



DUAL N-CHANNEL ENHANCEMENT MODE MOSFET POWERDI[®]

Product Summary

| V _{(BR)DSS} | R _{DS(ON)} max | I _D max T _A = +25°C |
|----------------------|---------------------------------|--|
| | 10.8mΩ @ $V_{GS} = 4.5V$ | 10.7A |
| 20V | 14.5mΩ @ $V_{GS} = 2.5V$ | 9.3A |
| | 17.0mΩ @ V _{GS} = 1.8V | 8.6A |

Description

This new generation MOSFET has been designed to minimize the onstate resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- **Power Management Functions**
- Load Switch

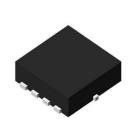
Features

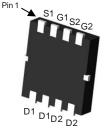
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- ESD Protected Up to 2kV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

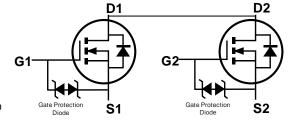
- Case: POWERDI®3333-8
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.0065 grams (Approximate)

POWERDI®3333-8









Top View

Bottom View

Internal Schematic

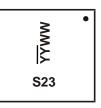
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|----------------|------------------|
| DMN2022UNS-7 | POWERDI®3333-8 | 2000/Tape & Reel |
| DMN2022UNS-13 | POWERDI®3333-8 | 3000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



S23 = Product Type Marking Code $\overline{YY}WW = Date Code Marking$ YY = Last Digit of Year (ex: 15 = 2015) WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units | | |
|---|------------------|--|------------------|--------------|----|
| Drain-Source Voltage | V _{DSS} | 20 | V | | |
| Gate-Source Voltage | | | V _{GSS} | ±10 | V |
| Continuous Prain Current (Note 6) V 40V | Steady State | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | 10.7 8.6 | А |
| Continuous Drain Current (Note 6) V _{GS} = 10V | t<10s | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | 13.9 11.1 | А |
| Maximum Body Diode Forward Current (Note 6) | | | Is | 2 | Α |
| Pulsed Drain Current (10μs pulse, Duty cycle = 1%) | | | I _{DM} | 60 | Α |
| Avalanche Current (Note 7) L = 0.1mH | | | I _{AS} | 17.1 | Α |
| Avalanche Energy (Note 7) L = 0.1mH | | | E _{AS} | 14.7 | mJ |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units | |
|--|--------------|-----------------------------------|-------------|------|
| Total Power Dissipation (Note 5) | | P_{D} | 1.2 | W |
| Thermal Desigtance Junction to Ambient (Note 5) | Steady State | D. | 107 | °C/W |
| Thermal Resistance, Junction to Ambient (Note 5) | t<10s | $R_{\theta JA}$ | 64 | |
| Total Power Dissipation (Note 6) | | P _D | 1.9 | W |
| Thermal Begistenes, Junction to Ambient (Note C) | Steady State | <u> </u> | 67 | °C/W |
| Thermal Resistance, Junction to Ambient (Note 6) | t<10s | $R_{\theta JA}$ | 40 | |
| Operating and Storage Temperature Range | | T _J , T _{STG} | -55 to +150 | °C |

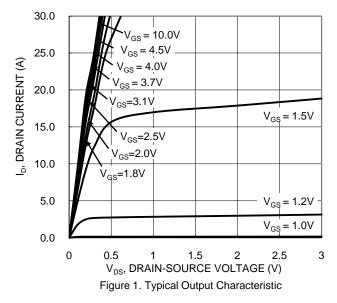
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|--|---------------------|-----|------|------|------|--|
| OFF CHARACTERISTICS (Note 8) | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 20 | _ | _ | V | $V_{GS} = 0V, I_D = 250\mu A$ |
| Zero Gate Voltage Drain Current T _J = +25°C | I _{DSS} | | | 1 | μΑ | $V_{DS} = 20V$, $V_{GS} = 0V$ |
| Gate-Source Leakage | I _{GSS} | | _ | ±10 | μΑ | $V_{GS} = \pm 10V$, $V_{DS} = 0V$ |
| ON CHARACTERISTICS (Note 8) | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | 0.4 | _ | 1 | V | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ |
| | | - | 9.0 | 10.8 | | $V_{GS} = 4.5V, I_D = 4A$ |
| | | | 9.2 | 11.2 | | $V_{GS} = 4.0V, I_{D} = 4A$ |
| Static Drain-Source On-Resistance | R _{DS(ON)} | | 9.8 | 13.0 | mΩ | $V_{GS} = 3.1V, I_D = 4A$ |
| | | | 10.5 | 14.5 | | $V_{GS} = 2.5V, I_D = 4A$ |
| | | | 13.9 | 17.0 | | $V_{GS} = 1.8V, I_D = 4A$ |
| Diode Forward Voltage | V_{SD} | | 0.7 | 1.1 | V | $V_{GS} = 0V, I_{S} = 5A$ |
| DYNAMIC CHARACTERISTICS (Note 9) | | | | | | |
| Input Capacitance | C _{iss} | | 1870 | _ | pF | \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ |
| Output Capacitance | Coss | | 320 | _ | pF | $V_{DS} = 10V, V_{GS} = 0V,$ - f = 1.0MHz |
| Reverse Transfer Capacitance | C _{rss} | l | 160 | | рF | 1 – 1.0101112 |
| Gate Resistance | R_g | | 96 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ |
| Total Gate Charge | Q_g | | 20.3 | _ | nC | \\\\ 4.5\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\ |
| Gate-Source Charge | Q_{gs} | | 2.8 | _ | nC | $V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 6.5A$ |
| Gate-Drain Charge | Q_{gd} | _ | 3.6 | _ | nC | ID = 6.5A |
| Turn-On Delay Time | t _{D(ON)} | _ | 62 | _ | ns | |
| Turn-On Rise Time | t _R | | 101 | _ | ns | V _{GS} = 4.5V, V _{DS} = 10V, |
| Turn-Off Delay Time | t _{D(OFF)} | | 596 | _ | ns | $R_G = 6\Omega$, $R_L = 1.0\Omega$ |
| Turn-Off Fall Time | t _F | | 224 | _ | ns |] |
| Reverse Recovery Time | t _{RR} | _ | 150 | _ | ns | $I_F = 4A$, $di/dt = 100A/\mu s$ |
| Reverse Recovery Charge | Q_{RR} | 1 | 135 | _ | nC | $I_F = 4A$, di/dt = 100A/ μ s |

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- Device mounted on FR-4 FC board, with minimum recommended pad layout, single steed.
 Device mounted on FR-4 SC board, with minimum recommended pad layout, single steed.
 I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to production testing.





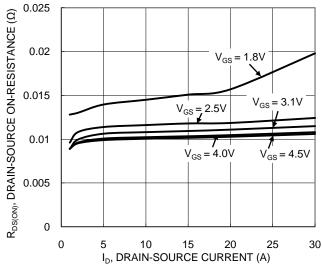


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

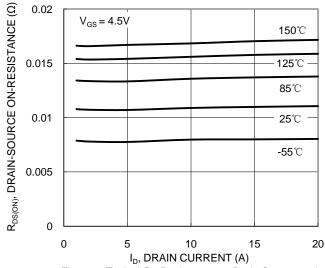
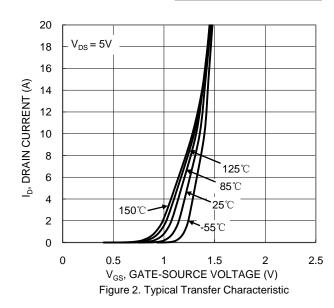
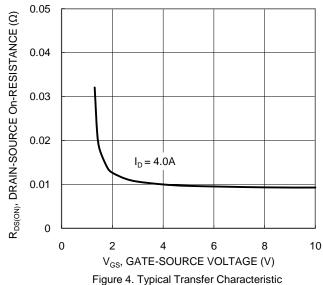


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





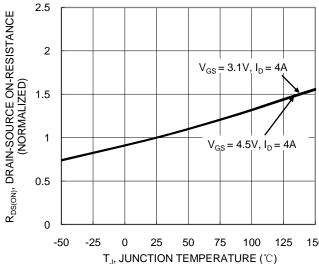


Figure 6. On-Resistance Variation with Junction Temperature



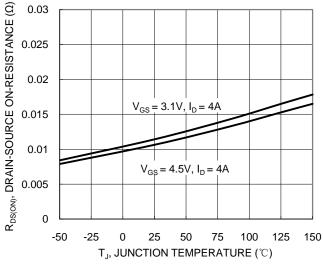


Figure 7. On-Resistance Variation with Junction Temperature

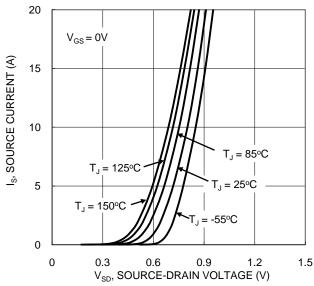
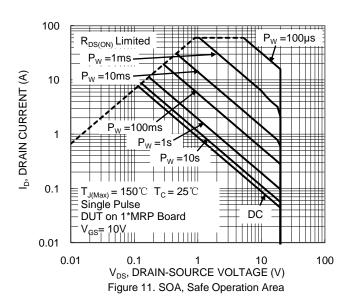


Figure 9. Diode Forward Voltage vs. Current



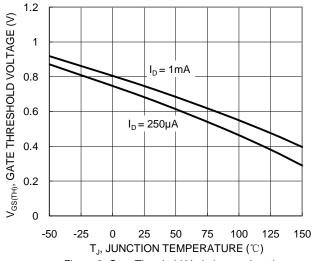


Figure 8. Gate Threshold Variation vs. Junction Temperature

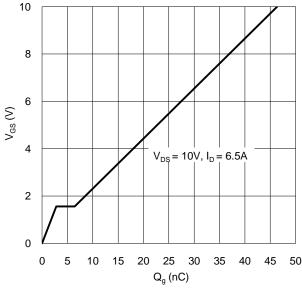


Figure 10. Gate Charge



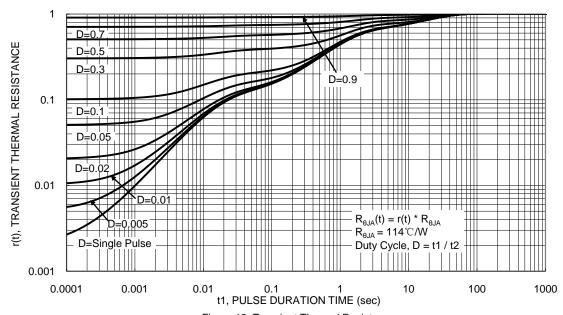


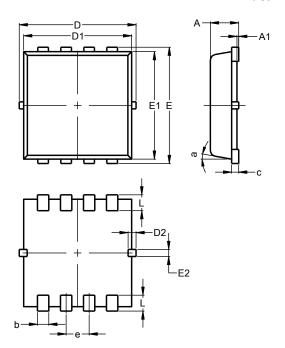
Figure 12. Transient Thermal Resistance



Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

POWERDI®3333-8 (Type UXB)

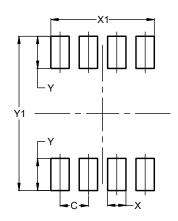


| POWERDI®3333-8 | | | | | | |
|----------------------|------|------|------|--|--|--|
| (Type UXB) | | | | | | |
| Dim | Min | Max | Тур | | | |
| Α | 0.75 | 0.85 | 0.80 | | | |
| A 1 | 0.00 | 0.05 | | | | |
| b | 0.25 | 0.40 | 0.32 | | | |
| С | 0.10 | 0.25 | 0.15 | | | |
| D | 3.20 | 3.40 | 3.30 | | | |
| D1 | 2.95 | 3.15 | 3.05 | | | |
| D2 | 0.10 | 0.35 | 0.23 | | | |
| Е | 3.20 | 3.40 | 3.30 | | | |
| E1 | 2.95 | 3.15 | 3.05 | | | |
| E2 | 0.10 | 0.30 | 0.20 | | | |
| е | _ | _ | 0.65 | | | |
| L | 0.35 | 0.55 | 0.45 | | | |
| а | 0° | 12° | 10° | | | |
| All Dimensions in mm | | | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

POWERDI®3333-8 (Type UXB)



| Dimensions | Value (in mm) | | | |
|------------|---------------|--|--|--|
| С | 0.650 | | | |
| Х | 0.420 | | | |
| X1 | 2.370 | | | |
| Y | 0.730 | | | |
| Y1 | 3 500 | | | |



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